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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	H8S/2000
Core Size	16-Bit
Speed	13MHz
Connectivity	SCI, SmartCard
Peripherals	DMA, POR, PWM, WDT
Number of I/O	87
Program Memory Size	-
Program Memory Type	ROMIess
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	120-TQFP
Supplier Device Package	120-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/d12352te13v

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2.4 Register Configuration

2.4.1 Overview

The CPU has the internal registers shown in figure 2-4. There are two types of registers: general registers and control registers.



Figure 2-4 CPU Registers

2.4.2 General Registers

The CPU has eight 32-bit general registers. These general registers are all functionally alike and can be used as both address registers and data registers. When a general register is used as a data register, it can be accessed as a 32-bit, 16-bit, or 8-bit register. When the general registers are used as 32-bit registers or address registers, they are designated by the letters ER (ER0 to ER7).

The ER registers divide into 16-bit general registers designated by the letters E (E0 to E7) and R (R0 to R7). These registers are functionally equivalent, providing a maximum sixteen 16-bit registers. The E registers (E0 to E7) are also referred to as extended registers.

4.2.3 Reset Sequence

The H8S/2357 Group enters the reset state when the $\overline{\text{RES}}$ pin goes low.

To ensure that the H8S/2357 Group is reset, hold the $\overline{\text{RES}}$ pin low for at least 20 ms at power-up. To reset the H8S/2357 Group during operation, hold the $\overline{\text{RES}}$ pin low for at least 20 states.

When the $\overline{\text{RES}}$ pin goes high after being held low for the necessary time, the H8S/2357 Group starts reset exception handling as follows:

- 1. The internal state of the CPU and the registers of the on-chip supporting modules are initialized, the T bit is cleared to 0 in EXR, and the I bit is set to 1 in EXR and CCR.
- 2. The reset exception handling vector address is read and transferred to the PC, and program execution starts from the address indicated by the PC.

Figure 4-2 show examples of the reset sequence.



Figure 4-2 Reset Sequence (Mode 4)

	Origin of		Vector Address*		
Interrupt Source	Interrupt Source	Vector Number	Advanced Mode	IPR	Priority
ERI0 (receive error 0)	SCI	80	H'0140	IPRJ2 to 0	High
RXI0 (reception data full 0)	channel 0	81	H'0144		•
TXI0 (transmit data empty 0)		82	H'0148		T
TEI0 (transmission end 0)		83	H'014C		
ERI1 (receive error 1)	SCI	84	H'0150	IPRK6 to 4	
RXI1 (reception data full 1)	channel 1	85	H'0154		
TXI1 (transmit data empty 1)		86	H'0158		
TEI1 (transmission end 1)		87	H'015C		
ERI2 (receive error 2)	SCI	88	H'0160	IPRK2 to 0	
RXI2 (reception data full 2)	channel 2	89	H'0164		
TXI2 (transmit data empty 2)		90	H'0168		
TEI2 (transmission end 2)		91	H'016C		Low

Note: * Lower 16 bits of the start address.

5.4 Interrupt Operation

5.4.1 Interrupt Control Modes and Interrupt Operation

Interrupt operations in the H8S/2357 Group differ depending on the interrupt control mode.

NMI interrupts are accepted at all times except in the reset state and the hardware standby state. In the case of IRQ interrupts and on-chip supporting module interrupts, an enable bit is provided for each interrupt. Clearing an enable bit to 0 disables the corresponding interrupt request. Interrupt sources for which the enable bits are set to 1 are controlled by the interrupt controller.

Table 5-5 shows the interrupt control modes.

The interrupt controller performs interrupt control according to the interrupt control mode set by the INTM1 and INTM0 bits in SYSCR, the priorities set in IPR, and the masking state indicated by the I and UI bits in the CPU's CCR, and bits I2 to I0 in EXR.

Table 5-5	Interrupt Control Modes
-----------	--------------------------------

Interrupt	SY	SCR	Priority Setting	Interrupt	
Control Mode	INTM1	INTM0	Registers	Mask Bits	Description
0	0	0	_	I	Interrupt mask control is performed by the I bit.
_	_	1	_	—	Setting prohibited
2	1	0	IPR	l2 to l0	8-level interrupt mask control is performed by bits I2 to I0. 8 priority levels can be set with IPR.
_	_	1	_	_	Setting prohibited



Figure 6-25 CBR Refresh Timing

When the RCW bit is set to 1, \overline{RAS} signal output is delayed by one cycle. The width of the \overline{RAS} signal should be adjusted with bits RLW1 and RLW0. These bits are only enabled in refresh operations.

Figure 6-26 shows the timing when the RCW bit is set to 1.



Figure 6-26 CBR Refresh Timing (When RCW = 1, RLW1 = 0, RLW0 = 1)

Self-Refreshing: A self-refresh mode (battery backup mode) is provided for DRAM as a kind of standby mode. In this mode, refresh timing and refresh addresses are generated within the DRAM.

To select self-refreshing, set the RFSHE bit and RMODE bit in DRAMCR to 1. Then, when a SLEEP instruction is executed to enter software standby mode, the \overline{CAS} and \overline{RAS} signals are output and DRAM enters self-refresh mode, as shown in figure 6-27.

When software standby mode is exited, the RMODE bit is cleared to 0 and self-refresh mode is cleared.

When switching to software standby mode, if there is a CBR refresh request, CBR refreshing is executed before self-refresh mode is entered.

6.10 Bus Release

6.10.1 Overview

The H8S/2357 Group can release the external bus in response to a bus request from an external device. In the external bus released state, the internal bus master continues to operate as long as there is no external access.

If an internal bus master wants to make an external access in the external bus released state, or if a refresh request is generated, it can issue a bus request off-chip.

6.10.2 Operation

In external expansion mode, the bus can be released to an external device by setting the BRLE bit in BCRL to 1. Driving the \overline{BREQ} pin low issues an external bus request to the H8S/2357 Group. When the \overline{BREQ} pin is sampled, at the prescribed timing the \overline{BACK} pin is driven low, and the address bus, data bus, and bus control signals are placed in the high-impedance state, establishing the external bus-released state.

In the external bus released state, an internal bus master can perform accesses using the internal bus. When an internal bus master wants to make an external access, it temporarily defers activation of the bus cycle, and waits for the bus request from the external bus master to be dropped. Even if a refresh request is generated in the external bus released state, refresh control is deferred until the external bus master drops the bus request.

If the BREQOE bit in BCRL is set to 1, when an internal bus master wants to make an external access in the external bus released state, or when a refresh request is generated, the \overline{BREQO} pin is driven low and a request can be made off-chip to drop the bus request.

When the \overline{BREQ} pin is driven high, the \overline{BACK} pin is driven high at the prescribed timing and the external bus released state is terminated.

If an external bus release request and external access occur simultaneously, the order of priority is as follows:

(High) External bus release > Internal bus master external access (Low)

If a refresh request and external bus release request occur simultaneously, the order of priority is as follows:

(High) Refresh > External bus release (Low)

As a refresh and an external access by an internal bus master can be executed simultaneously, there is no relative order of priority for these two operations.

7.7 Usage Notes

DMAC Register Access during Operation: Except for forced termination, the operating (including transfer waiting state) channel setting should not be changed. The operating channel setting should only be changed when transfer is disabled.

Also, the DMAC register should not be written to in a DMA transfer.

DMAC register reads during operation (including the transfer waiting state) are described below.

(a) DMAC control starts one cycle before the bus cycle, with output of the internal address. Consequently, MAR is updated in the bus cycle before DMAC transfer.

Figure 7-40 shows an example of the update timing for DMAC registers in dual address transfer mode.



Figure 7-40 Example of DMAC Register Update Timing

Example of Buffer Operation Setting Procedure: Figure 10-18 shows an example of the buffer operation setting procedure.



Figure 10-18 Example of Buffer Operation Setting Procedure

Examples of Buffer Operation

• When TGR is an output compare register

Figure 10-19 shows an operation example in which PWM mode 1 has been designated for channel 0, and buffer operation has been designated for TGRA and TGRC. The settings used in this example are TCNT clearing by compare match B, 1 output at compare match A, and 0 output at compare match B.

As buffer operation has been set, when compare match A occurs the output changes and the value in buffer register TGRC is simultaneously transferred to timer general register TGRA. This operation is repeated each time compare match A occurs.

For details of PWM modes, see section 10.4.6, PWM Modes.



Figure 10-19 Example of Buffer Operation (1)

12.2.5 Timer Control/Status Registers 0 and 1 (TCSR0, TCSR1)

TCSR0

Bit :	7	6	5	4	3	2	1	0
	CMFB	CMFA	OVF	ADTE	OS3	OS2	OS1	OS0
Initial value :	0	0	0	0	0	0	0	0
R/W :	R/(W)*	R/(W)*	R/(W)*	R/W	R/W	R/W	R/W	R/W
TCSR1								
Bit :	7	6	5	4	3	2	1	0
	CMFB	CMFA	OVF	_	OS3	OS2	OS1	OS0
Initial value :	0	0	0	1	0	0	0	0
R/W :	R/(W)*	R/(W)*	R/(W)*	_	R/W	R/W	R/W	R/W

Note: * Only 0 can be written to bits 7 to 5, to clear these flags.

TCSR0 and TCSR1 are 8-bit registers that display compare match and overflow statuses, and control compare match output.

TCSR0 is initialized to H'00, and TCSR1 to H'10, by a reset and in hardware standby mode.

Bit 7—Compare Match Flag B (CMFB): Status flag indicating whether the values of TCNT and TCORB match.

Bit 7 CMFB	Description
0	[Clearing conditions] (Initial value)
	 Cleared by reading CMFB when CMFB = 1, then writing 0 to CMFB
	 When DTC is activated by CMIB interrupt while DISEL bit of MRB in DTC is 0
1	[Setting condition]
	Set when TCNT matches TCORB

Bit 6—Compare Match Flag A (CMFA): Status flag indicating whether the values of TCNT and TCORA match.

Bit 6 CMFA	Description	
0	[Clearing conditions]	(Initial value)
	• Cleared by reading CMFA when CMFA = 1, then writing 0 to CMFA	
	When DTC is activated by CMIA interrupt while DISEL bit of MRB in	DTC is 0
1	[Setting condition]	
	Set when TCNT matches TCORA	

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Figure 14-13 shows an example of SCI operation for multiprocessor format reception.

Figure 14-13 Example of SCI Operation in Reception (Example with 8-Bit Data, Multiprocessor Bit, One Stop Bit)

Section 15 Smart Card Interface

15.1 Overview

SCI supports an IC card (Smart Card) interface conforming to ISO/IEC 7816-3 (Identification Card) as a serial communication interface extension function.

Switching between the normal serial communication interface and the Smart Card interface is carried out by means of a register setting.

15.1.1 Features

Features of the Smart Card interface supported by the H8S/2357 Group are as follows.

- Asynchronous mode
 - Data length: 8 bits
 - Parity bit generation and checking
 - Transmission of error signal (parity error) in receive mode
 - Error signal detection and automatic data retransmission in transmit mode
 - Direct convention and inverse convention both supported
- On-chip baud rate generator allows any bit rate to be selected
- Three interrupt sources
 - Three interrupt sources (transmit data empty, receive data full, and transmit/receive error) that can issue requests independently
 - The transmit data empty interrupt and receive data full interrupt can activate the DMA controller (DMAC) or data transfer controller (DTC) to execute data transfer

16.2.4 Module Stop Control Register (MSTPCR)



MSTPCR is a 16-bit readable/writable register that performs module stop mode control.

When the MSTP9 bit in MSTPCR is set to 1, A/D converter operation stops at the end of the bus cycle and a transition is made to module stop mode. Registers cannot be read or written to in module stop mode. For details, see section 21.5, Module Stop Mode.

MSTPCR is initialized to H'3FFF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 9—Module Stop (MSTP9): Specifies the A/D converter module stop mode.

Bit 9 MSTP9	Description	
0	A/D converter module stop mode cleared	
1	A/D converter module stop mode set	(Initial value)

18.2 Register Descriptions

Bit	:	7	6	5	4	3	2	1	0
		_	—	INTM1	INTM0	NMIEG	—	—	RAME
Initial va	lue :	0	0	0	0	0	0	0	1
R/W	:	R/W	—	R/W	R/W	R/W	—	R/W	R/W

18.2.1 System Control Register (SYSCR)

The on-chip RAM is enabled or disabled by the RAME bit in SYSCR. For details of other bits in SYSCR, see section 3.2.2, System Control Register (SYSCR).

Bit 0—RAM Enable (RAME): Enables or disables the on-chip RAM. The RAME bit is initialized when the reset state is released. It is not initialized in software standby mode.

Bit 0		
RAME	Description	
0	On-chip RAM is disabled	
1	On-chip RAM is enabled	(Initial value)

18.3 Operation

When the RAME bit is set to 1, accesses to addresses H'FFDC00 to H'FFFBFF* are directed to the on-chip RAM. When the RAME bit is cleared to 0, the off-chip address space is accessed.

Since the on-chip RAM is connected to the CPU by an internal 16-bit data bus, it can be written to and read in byte or word units. Each type of access can be performed in one state.

Even addresses use the upper 8 bits, and odd addresses use the lower 8 bits. Word data must start at an even address.

Note: * Since the on-chip RAM capacitance differs according to each product, see section 3.5, Memory Map in Each Operating Mode.

18.4 Usage Note

DTC register information can be located in addresses H'FFF800 to H'FFFBFF. When the DTC is used, the RAME bit must not be cleared to 0.

19.15.5 Flash Memory Emulation in RAM

Reading Overlap RAM Data in User Mode and User Program Mode: Emulation should be performed in user mode or user program mode. When the emulation block set in RAMER is accessed while the emulation function is being executed, data written in the overlap RAM is read.



Figure 19-40 Reading Overlap RAM Data in User Mode and User Program Mode

Writing Overlap RAM Data in User Program Mode: When overlap RAM data is confirmed, the RAMS bit is cleared, RAM overlap is released, and writes should actually be performed to the flash memory.

When the programming control program is transferred to RAM, ensure that the transfer destination and the overlap RAM do not overlap, as this will cause data in the overlap RAM to be rewritten.



Figure 19-41 Writing Overlap RAM Data in User Program Mode



Figure 22-51 DMAC Single Address Transfer Timing (Three-State Access)



Figure 22-52 DMAC TEND Output Timing



Figure 22-53 DMAC DREQ Intput Timing

Item		Symbol	Min	Тур	Max	Unit	Test Condition
Programming	Wait time after SWE bit clear* 1	θ	100	_	—	μs	
	Maximum programming count*1*4	Ν	_	—	1000*5	Times	
Erase	Wait time after SWE bit setting*1	х	1		—	μs	
	Wait time after ESU bit setting*1	у	100	_	—	μs	
	Wait time after E bit setting*1*6	Z	_	_	10	ms	Erase time wait
	Wait time after E bit clear*1	α	10	—		μs	
	Wait time after ESU bit clear*1	β	10	—	_	μs	
	Wait time after EV bit setting*1	γ	20	—		μs	
	Wait time after H'FF dummy write*1	ε	2		_	μs	
	Wait time after EV bit clear*1	η	4	_	_	μs	
	Wait time after SWE bit clear*1	θ	100	—	_	μs	
	Maximum erase count*1*6	Ν	—	—	100	Times	

Notes: 1. Settings of each time must comply with algorithm of writing/erasing.

2. Writing time for 128 bytes: indicates the total period in which bit P of flash memory control register 1 (FLMCR1) is set. Writing verification time is not included.

3. Erasing time for one block: indicates the period in which bit E of FLMCR1 is set. Erasing verification time is not included.

- 4. Maximum writing time: $t_P(max) = \Sigma$ wait time (z) after setting of bit P
- The maximum writing count (N) must be set to the maximum writing time (t_P(max)) or less according the actual set value (z). Wait time (z) must be switched after setting of bit P according to writing count (n). Writing count n

$$\begin{split} 1 &\leq n \leq 6 \qquad z = 30 \ \mu s \\ 7 &\leq n \leq 1000 \qquad z = 200 \ \mu s \\ \text{[In additional writing]} \\ \text{Writing count n} \\ 1 &\leq n \leq 6 \qquad z = 10 \ \mu s \end{split}$$

 Wait time (z) after setting of bit E and the maximum erasing count (N) have the following relationship to the maximum erasing time (t_e(max)).

 $t_{E}(max)$ = wait time (z) after setting of bit E × maximum erasing count (N)

Instruction	-	2	3	4	5	9	7	8	6
MOV.W Rs, @(d:16,ERd)	R:W 2nd	R:W NEXT	W:W EA						
MOV.W Rs, @(d:32,ERd)	R:W 2nd	R:W 3rd	R:E 4th	R:W NEXT	W:W EA				
MOV.W Rs, @-ERd	R:W NEXT	Internal operation, 1 state	W:W EA						
MOV.W Rs, @aa:16	R:W 2nd	R:W NEXT	W:W EA						
MOV.W Rs, @aa:32	R:W 2nd	R:W 3rd	R:W NEXT	W:W EA					
MOV.L #xx:32,ERd	R:W 2nd	R:W 3rd	R:W NEXT						
MOV.L ERS, ERd	R:W NEXT								
MOV.L @ERs,ERd	R:W 2nd	R:W:M NEXT	R:W:M EA	R:W EA+2					
MOV.L @(d:16,ERs),ERd	R:W 2nd	R:W:M 3rd	R:W NEXT	R:W:M EA	R:W EA+2				
MOV.L @(d:32,ERs),ERd	R:W 2nd	R:W:M 3rd	R:W:M 4th	R:W 5th	R:W NEXT	R:W:M EA	R:W EA+2		
MOV.L @ERs+,ERd	R:W 2nd	R:W:M NEXT	Internal operation,	R:W:M EA	R:W EA+2				
			1 state						
MOV.L @aa:16,ERd	R:W 2nd	R:W:M 3rd	R:W NEXT	R:W:M EA	R:W EA+2				
MOV.L @aa:32,ERd	R:W 2nd	R:W:M 3rd	R:W 4th	R:W NEXT	R:W:M EA	R:W EA+2			
MOV.L ERS, @ERd	R:W 2nd	R:W:M NEXT	W:W:M EA	W:W EA+2					
MOV.L ERs,@(d:16,ERd)	R:W 2nd	R:W:M 3rd	R:W NEXT	W:W:M EA	W:W EA+2				
MOV.L ERs, @(d:32, ERd)	R:W 2nd	R:W:M 3rd	R:W:M 4th	R:W 5th	R:W NEXT	W:W:M EA	W:W EA+2		
MOV.L ERs, @-ERd	R:W 2nd	R:W:M NEXT	Internal operation,	W:W:M EA	W:W EA+2				
			1 state						
MOV.L ERs,@aa:16	R:W 2nd	R:W:M 3rd	R:W NEXT	W:W:M EA	W:W EA+2				
MOV.L ERs,@aa:32	R:W 2nd	R:W:M 3rd	R:W 4th	R:W NEXT	W:W:M EA	W:W EA+2			
MOVFPE @aa:16,Rd	Cannot be use	ed in the H8S/23	57 Group						
MOVTPE Rs,@aa:16									
MULXS.B Rs,Rd	R:W 2nd	R:W NEXT	Internal operati	ion, 11 states					
MULXS.W Rs, ERd	R:W 2nd	R:W NEXT	Internal operati	ion, 19 states					
MULXU.B Rs,Rd	R:W NEXT	Internal operati	on, 11 states						
MULXU.W RS,ERd	R:W NEXT	Internal operati	on, 19 states						
NEG.B Rd	R:W NEXT								
NEG.W Rd	R:W NEXT								
NEG.L ERd	R:W NEXT								
NOP	R:W NEXT								
NOT.B Rd	R:W NEXT								
NOT.W Rd	R:W NEXT								
NOT.L ERd	R:W NEXT								
OR.B #xx:8,Rd	R:W NEXT								
OR.B Rs,Rd	R:W NEXT								

		-	>	-	>	>		0
MOV.W Rs, @(d:16,ERd)	R:W 2nd	R:W NEXT	W:W EA					
MOV.W Rs, @(d:32, ERd)	R:W 2nd	R:W 3rd	R:E 4th	R:W NEXT	W:W EA			
MOV.W Rs, @-ERd	R:W NEXT	Internal operation,	W:W EA					
		1 state						
MOV.W Rs,@aa:16	R:W 2nd	R:W NEXT	W:W EA					
MOV.W Rs, @aa:32	R:W 2nd	R:W 3rd	R:W NEXT	W:W EA				
MOV.L #xx:32,ERd	R:W 2nd	R:W 3rd	R:W NEXT					
MOV.L ERS, ERd	R:W NEXT							
MOV.L @ERs,ERd	R:W 2nd	R:W:M NEXT	R:W:M EA	R:W EA+2				
MOV.L @(d:16,ERs),ERd	R:W 2nd	R:W:M 3rd	R:W NEXT	R:W:M EA	R:W EA+2			
MOV.L @(d:32,ERs),ERd	R:W 2nd	R:W:M 3rd	R:W:M 4th	R:W 5th	R:W NEXT	R:W:M EA	R:W EA+2	
MOV.L @ERs+,ERd	R:W 2nd	R:W:M NEXT	Internal operation, 1 state	R:W:M EA	R:W EA+2			
MOV.L @aa:16,ERd	R:W 2nd	R:W:M 3rd	R:W NEXT	R:W:M EA	R:W EA+2			
MOV.L @aa:32,ERd	R:W 2nd	R:W:M 3rd	R:W 4th	R:W NEXT	R:W:M EA	R:W EA+2		
MOV.L ERs,@ERd	R:W 2nd	R:W:M NEXT	W:W:MEA	W:W EA+2				
MOV.L ERs, @(d:16, ERd)	R:W 2nd	R:W:M 3rd	R:W NEXT	W:W:M EA	W:W EA+2			
MOV.L ERs, @(d:32, ERd)	R:W 2nd	R:W:M 3rd	R:W:M 4th	R:W 5th	R:W NEXT	W:W:M EA	W:W EA+2	
MOV.L ERs,@-ERd	R:W 2nd	R:W:M NEXT	Internal operation,	W:W:M EA	W:W EA+2			
			1 state					
MOV.L ERs,@aa:16	R:W 2nd	R:W:M 3rd	R:W NEXT	W:W:M EA	W:W EA+2			
MOV.L ERs,@aa:32	R:W 2nd	R:W:M 3rd	R:W 4th	R:W NEXT	W:W:M EA	W:W EA+2		
MOVFPE @aa:16,Rd	Cannot be use	d in the H8S/235	7 Group					
MOVTPE Rs,@aa:16								
MULXS.B Rs,Rd	R:W 2nd	R:W NEXT	Internal operation	on, 11 states				
MULXS.W Rs, ERd	R:W 2nd	R:W NEXT	Internal operation	on, 19 states				
MULXU.B Rs,Rd	R:W NEXT	Internal operati	on, 11 states					
MULXU.W RS, ERd	R:W NEXT	Internal operati	on, 19 states					
NEG.B Rd	R:W NEXT							
NEG.W Rd	R:W NEXT							
NEG.L ERd	R:W NEXT							
NOP	R:W NEXT							
NOT.B Rd	R:W NEXT							
NOT.W Rd	R:W NEXT							
NOT.L ERd	R:W NEXT							
OR.B #xx:8,Rd	R:W NEXT							
OR.B Rs,Rd	R:W NEXT							

ETCR0B—Transfer Count Register 0B H'FEEE DMAC

	Bit : ETCR0B : Initial value : Read/Write : Sequential mode and idle mode	15 	14 * 7 R/W	13 * 7 R/W	12 * R/W	11 * 7 R/W	10 * R/W	9 * 7 R/W	8 * 7 R/W	7 * 7 R/W	6 * / R/W	5 * / R/W	4 * 7 R/W	3 * 7 R/W	2 * 7 R/W	1 * 7 R/W	0
	Repeat mode	Tra	Transfer number storage register Transfer counter												er		
	Block transfer mode		Block transfer counter														
	Note: Not use	ed in ı	norma	al mo	de.										* :	Unde	əfined
MAR1AH—Memory Address Register 1AHH'FEF0DMACMAR1AL—Memory Address Register 1ALH'FEF2DMAC																	
	Bit :	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
	MAR1AH :	_	_	-	_	_	_	_	_								
	Initial value :	0	0	0	0	0	0	0	0	*	*	*	*	*	*	*	*
	Read/Write :	—	—	—	_	—	_	_	—	R/W	R/W						
	Bit :	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	MAR1AL :																
	Initial value :	*	*	*	*	*	*	*	*	*	*	*	*	*	*	*	*
	Read/Write :	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
															*:l	Jnde	fined
In short address mode: Specifies transfer source/transfer destination address In full address mode: Specifies transfer source address																	
IOAR1A—I/O Address Register 1A								H'FEF4					DMAC				
	Bit :	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	IOAR1A :																
	Initial value :	*	*	*	*	*	*	*	*	*	*	*	*	*	*	*	*
	Read/Write :	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	' R/W	/ R/W	/ R/W	' R/W	/ R/W	' R/W	R/W	' R/W

* : Undefined

In short address mode: Specifies transfer source/transfer destination address In full address mode: Not used



Figure C-6 (b) Port 6 Block Diagram (Pin P6₁)

C.8 Port B Block Diagram



Figure C-8 Port B Block Diagram (Pin PB₀ to PB₇)

C.9 Port C Block Diagram



Figure C-9 Port C Block Diagram (Pin PC₀ to PC₇)